

PRODUCT DATASHEET

D25 HF Glob Top Label –NXPNTAG213

Label Built to Resist Environmental Impact

Glob-top Smart Label is specially designed to increase its protection level for better resistibility against water and the environmental stress. The label body is enhanced in thickness for greater robustness while there is extra protection to the chip. Powered by NXP NTAG213, this label is compliant with ISO14443A and NFC forum type 2 RF interface protocol which facilitate easy and secure authenticity verification.

Features

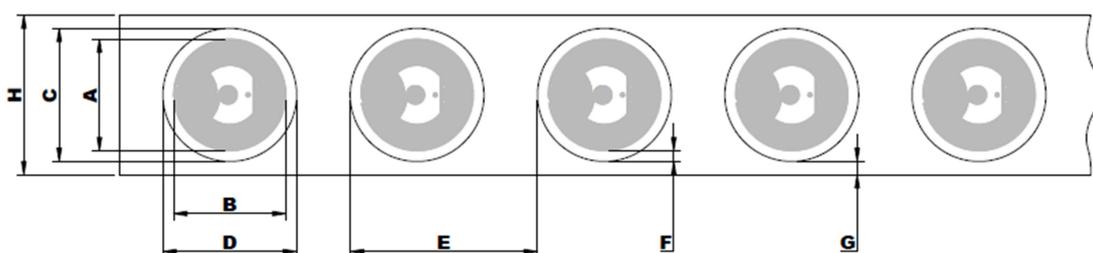
- Enhanced chip protection
- Increased label thickness

Applications

- Product Authentication
- Inventory Management



Physical Specification



A	Inlay Length	21 mm / 0.82 in	E	Label Pitch	35 mm / 1.37 in
B	Inlay Width	21 mm / 0.82 in	F	Inlay to Die Cut	2 mm / 0.07 in
C	Label Length	25 mm / 0.98 in	G	Die Cut to Web Edge	2.5 mm / 0.09 in
D	Label Width	25 mm / 0.98 in	H	Web Width	30 mm / 1.18 in

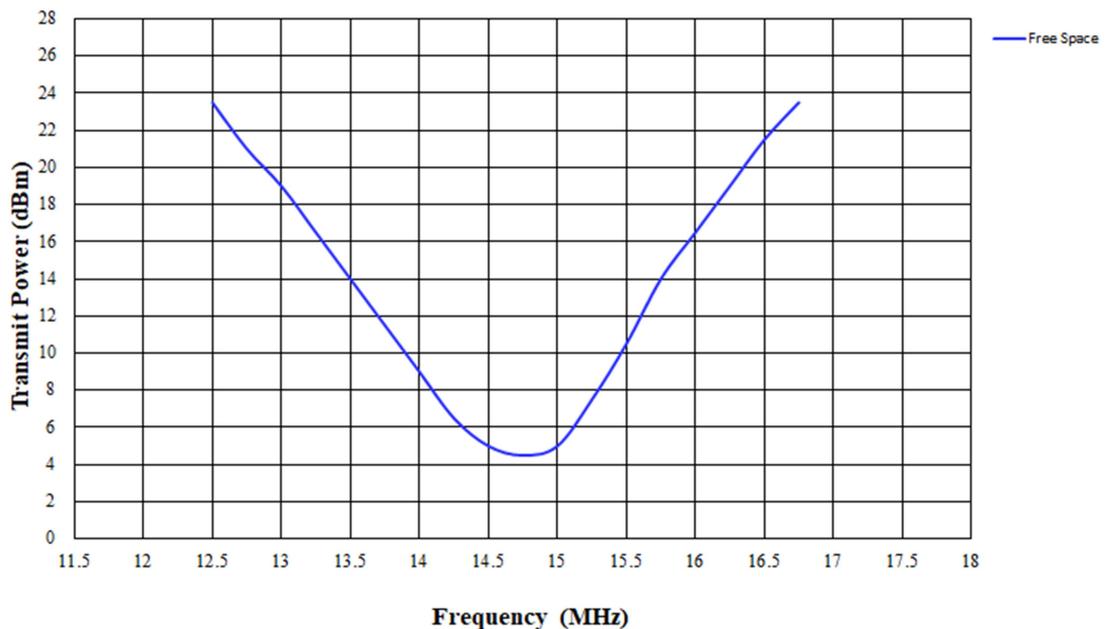
*The exact size is mainly based on metric unit.

Packing Criteria



RF Specification

RFID Chip	NXP NTAG 213
Memory	UID 7-byte / User 144 byte
RF Interface Protocol	ISO/IEC 14443 A / NFC Forum Type 2
Operating Frequency	13.56 MHz
Applicable Surface	Non-metal



*HF sensitivity shown in the figure is measured by Voyantic Tagformance HF Loop Antenna C60. Actual sensitivity performance is subject to the environment in practice.

Environmental Resistance

Operating Temperature	-25°C to 70°C
Storage Temperature	-25°C to 70°C
ESD Protection	±2 kV peak according to IEC 61000-4-2 Contact discharge
Warranty	One Year

Ref. No: Digi-key/441170538-01071

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